

=> file reg

FILE 'REGISTRY' ENTERED AT 22:09:20 ON 18 MAY 2006
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=> d his

FILE 'HCAPLUS' ENTERED AT 21:15:18 ON 18 MAY 2006

L1 13619 S HUBER ?/AU
L2 892 S DEO ?/AU
L3 17 S MERCHAK ?/AU
L4 2978 S CHAMBERLAIN ?/AU
L5 20829 S SCHWARTZ ?/AU
L6 1 S L1 AND L2 AND L3 AND L4 AND L5

FILE 'REGISTRY' ENTERED AT 21:17:15 ON 18 MAY 2006

L7 1 S 528-44-9
E 1,2,4-BENZENETRICARBOXYLIC ACID ANHYDRIDE/CN
L8 1 S E1
L9 1 S 83713-01-3
L10 659 S 6168-72-5/CRN
L11 27425 S 75-21-8/CRN
L12 20736 S 75-56-9/CRN
L13 15814 S 67-56-1/CRN
L14 147 S L10 AND (L11 OR L12) AND L13

FILE 'HCA' ENTERED AT 21:21:59 ON 18 MAY 2006

L15 340 S L9 OR L14
L16 4771 S L7 OR L8
L17 2 S L15 AND L16

FILE 'REGISTRY' ENTERED AT 21:24:19 ON 18 MAY 2006

L18 552 S JEFFAMINE#

FILE 'HCA' ENTERED AT 21:25:12 ON 18 MAY 2006

L19 5296 S L18 OR JEFFAMINE#
L20 38 S L19 AND L16
L21 79724 S INK?
L22 1 S L20 AND L21

FILE 'REGISTRY' ENTERED AT 21:28:27 ON 18 MAY 2006

L23 2 S L7 OR L8
SEL L23 1-2 RN
EDIT E1-E2 /BI /CRN
L24 10410 S E1-E2

L25 9 S L24 AND (L11 OR L12) AND L10
SEL L25 3 RN

L26 1 S E3

FILE 'HCA' ENTERED AT 21:32:39 ON 18 MAY 2006
L27 3 S L26

FILE 'REGISTRY' ENTERED AT 21:32:39 ON 18 MAY 2006
L28 21 S L24 AND L18
L29 18 S L28 NOT L25
SEL L29 7,8,9,10 RN
L30 4 S E4-E7

FILE 'HCA' ENTERED AT 21:39:32 ON 18 MAY 2006
L31 1 S L30

FILE 'LREGISTRY' ENTERED AT 21:41:17 ON 18 MAY 2006
L32 STR

FILE 'REGISTRY' ENTERED AT 21:43:29 ON 18 MAY 2006
L33 142175 S C2H4O OR C3H6O
L34 50 S L32 SSS SAM SUB=L33
L35 21 S L32
L36 SCR 1838 AND 1526
L37 21 S L32 AND L36
L38 SCR 2043
L39 50 S L32 AND L36 AND L38
L40 13586 S L32 AND L36 AND L38 FUL
SAV TEM L40 SHO212/A
L41 207 S L40 AND (L11 OR L12)
L42 9 S L41 AND L10
L43 21 S L40 AND L18
L44 0 S L42 NOT L25
L45 0 S L43 NOT L28
L46 STR
L47 STR
L48 50 S L46 SSS SAM SUB=L40
L49 STR L46
L50 50 S L49 SSS SAM SUB=L40
L51 19 S L49 AND L47 SSS SAM SUB=L40
L52 502 S L49 AND L47 SSS FUL SUB=L40
SAV L52 SHO212A/A
L53 3 S L52 AND (L11 OR L12)
L54 70 S L52 AND L33
L55 3 S 176429-11-1/CRN
L56 1 S L55 NOT L53

FILE 'HCA' ENTERED AT 21:57:30 ON 18 MAY 2006

L57 2 S L56

FILE 'REGISTRY' ENTERED AT 21:57:35 ON 18 MAY 2006

L58 35 S L54 NOT 5<NC

L59 1 S L58 NOT 46.150.18/RID

FILE 'LREGISTRY' ENTERED AT 22:05:33 ON 18 MAY 2006

L60 50160 S 46.150.18/RID

FILE 'REGISTRY' ENTERED AT 22:06:34 ON 18 MAY 2006

L61 7 S L54 NOT L60

L62 7 S L59 OR L61

FILE 'HCA' ENTERED AT 22:08:29 ON 18 MAY 2006

L63 8 S L17 OR L27 OR L31 OR L57

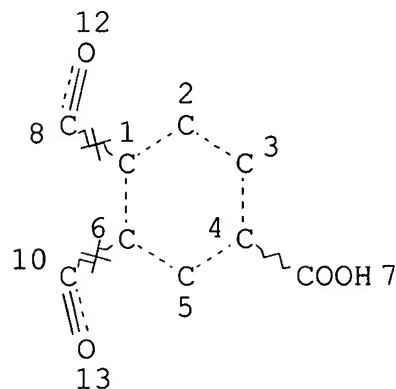
L64 35 S L20 NOT L63

L65 27 S L64 AND 1840-2003/PRY,PY

FILE 'REGISTRY' ENTERED AT 22:09:20 ON 18 MAY 2006

=> d 152 que stat

L32 STR



NODE ATTRIBUTES:

DEFAULT MLEVEL IS ATOM

DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:

RING(S) ARE ISOLATED OR EMBEDDED

NUMBER OF NODES IS 11

STEREO ATTRIBUTES: NONE

L36 SCR 1838 AND 1526

L38 SCR 2043

L40 13586 SEA FILE=REGISTRY SSS FUL L32 AND L36 AND L38

L47 STR

Ak~O
1 2

NODE ATTRIBUTES:

CONNECT IS E1 RC AT 1
DEFAULT MLEVEL IS ATOM
GGCAT IS SAT AT 1
DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:

RING(S) ARE ISOLATED OR EMBEDDED
NUMBER OF NODES IS 2

STEREO ATTRIBUTES: NONE

L49 STR

N—Ak—O
1 2 3

NODE ATTRIBUTES:

NSPEC IS RC AT 1
CONNECT IS E2 RC AT 2
DEFAULT MLEVEL IS ATOM
GGCAT IS SAT AT 2
DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:

RING(S) ARE ISOLATED OR EMBEDDED
NUMBER OF NODES IS 3

STEREO ATTRIBUTES: NONE

L52 502 SEA FILE=REGISTRY SUB=L40 SSS FUL L49 AND L47

100.0% PROCESSED 8250 ITERATIONS
SEARCH TIME: 00.00.01

502 ANSWERS

=> file hca

FILE 'HCA' ENTERED AT 22:10:03 ON 18 MAY 2006
USE IS SUBJECT TO THE TERMS OF YOUR STN CUSTOMER AGREEMENT.
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=> d 163 1-8 cbib abs hitstr hitind

L63 ANSWER 1 OF 8 HCA COPYRIGHT 2006 ACS on STN

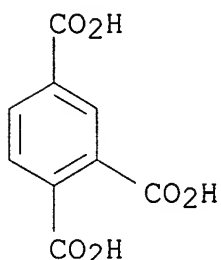
143:28236 Polymeric dispersant for printing ink composition. Huber, Gregory T.; Deo, Niranjana; Merchak, Paul A.; Chamberlain, Terence R.; Schwartz, Russell J. (USA). U.S. Pat. Appl. Publ. US 2005120911 A1 20050609, 5 pp. (English). CODEN: USXXCO. APPLICATION: US 2003-730212 20031205.

AB The polymeric dispersant prep'd. by reacting a polyoxyalkylene amine (e.g., XTJ 507) with 1,2,4-benzenetricarboxylic acid anhydride is used in printing inks. An energy-curable printing inks contg. the polymer dispersants have reduced viscosity and improved gloss.

IT **528-44-9DP**, 1,2,4-Benzenetricarboxylic acid, reaction products with polyoxyalkylene amine **83713-01-3DP**, XTJ 507, reaction products with benzenetricarboxylic acid anhydride (dispersant; polymeric dispersant for printing ink compn.)

RN 528-44-9 HCA

CN 1,2,4-Benzenetricarboxylic acid (8CI, 9CI) (CA INDEX NAME)



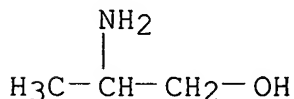
RN 83713-01-3 HCA

CN Oxirane, methyl-, polymer with oxirane, 2-aminopropyl methyl ether (9CI) (CA INDEX NAME)

CM 1

CRN 6168-72-5

CMF C3 H9 N O



CM 2

CRN 67-56-1

CMF C H4 O

H₃C-OH

CM 3

CRN 9003-11-6

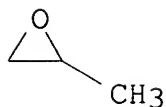
CMF (C₃ H₆ O . C₂ H₄ O) x

CCI PMS

CM 4

CRN 75-56-9

CMF C₃ H₆ O



CM 5

CRN 75-21-8

CMF C₂ H₄ O



IC ICM C09D011-00

INCL 106031490; 106031780

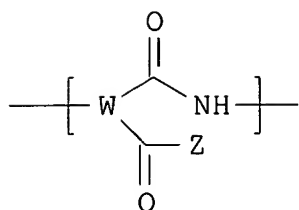
CC 42-12 (Coatings, Inks, and Related Products)

IT **528-44-9DP**, 1,2,4-Benzenetricarboxylic acid, reaction products with polyoxyalkylene amine **83713-01-3DP**, XTJ 507, reaction products with benzenetricarboxylic acid anhydride (dispersant; polymeric dispersant for printing ink compn.)

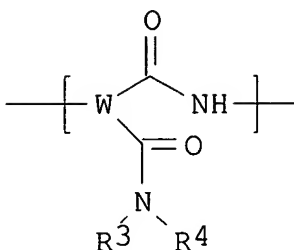
L63 ANSWER 2 OF 8 HCA COPYRIGHT 2006 ACS on STN

142:299823 Polyether-modified polymers as leather auxiliaries giving good fullness, softness, and tinctorial properties. Reiners, Juergen; Kleban, Martin; Brinkmann, Nils (Germany). U.S. Pat. Appl. Publ. US 2005058619 A1 20050317, 22 pp. (English). CODEN: USXXCO. APPLICATION: US 2004-941792 20040915. PRIORITY: DE 2003-10342926 20030917.

GI



I



II

AB The present invention relates to copolymers contg. (A) structural units I (B) .gtoreq.10 mol% (based on I) structural units II, and (C) polyether units with av. mol. wt. 200-6000 g/mol, wherein W = a trivalent radical; Z = OH, O-M⁺ or NR₁R₂; R₁, R₂ = H, (un)substituted alkyl radicals, alkenyl radicals, aralkyl radicals or cycloalkyl radicals which may be interrupted by O, N, Si, or amido, carbonate, urethane, urea, allophanate, biuret or isocyanurate groups or mixts. thereof; and M⁺ = H⁺ or alkali metal ion, NH₄ ion or a primary, secondary, tertiary or quaternary aliph. ammonium radical having C1-22 alkyl or hydroxyalkyl group; R₃ = C1-60 hydrocarbon, preferably satd. C1-60 alkyl radical, in particular C12-30 alkyl radical; and R₄ = H or C1-60 hydrocarbon, preferably satd. C1-60 alkyl radical, in particular C12-30 alkyl radical. Thus, 245.1 g maleic anhydride was heated at 65.degree., 500.0 g Jeffamine D 2000 was added therein and heated at 50-70.degree., 170.0 g 25% an aq. ammonia soln. was added therein at 50-60.degree. and heated at 70.degree. for 1 h, 168.5 g Armeen HT was added therein and heated at 140.degree. for 7 h, 42.0 g oleic acid was added therein, 2000 g water and 18.0 g ethanolamine were added therein while 80 g 50% a sodium hydroxide soln. was fed therein, 0.5 g Respumit S (antifoamer) was added therein, 100.0 g 35% hydrogen peroxide was added therein and heated, 1.0 g Respumit S and 3.0 g Baylase EPK were added therein and stirred at 35.degree. to give 30.7%-solids a copolymer soln. with Mw 11,200, mean particle size 140 n, and viscosity 510 mPa-s at 20.degree., showing good fullness, softness, and tinctorial properties when used for leather treatment.

IT **83713-01-3DP**, reaction products with maleic anhydride, ammonia, fatty amines, oleic acid, and ethanolamines (Jeffamine XTJ 507, Jeffamine XTJ 505; prepn. of polyether-modified polymers as leather auxiliaries giving good fullness, softness, and tinctorial properties)

RN 83713-01-3 HCA

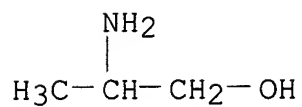
CN Oxirane, methyl-, polymer with oxirane, 2-aminopropyl methyl ether

(9CI) (CA INDEX NAME)

CM 1

CRN 6168-72-5

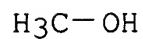
CMF C3 H9 N O



CM 2

CRN 67-56-1

CMF C H4 O



CM 3

CRN 9003-11-6

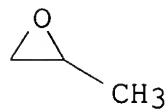
CMF (C3 H6 O . C2 H4 O) x

CCI PMS

CM 4

CRN 75-56-9

CMF C3 H6 O



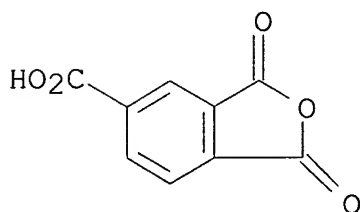
CM 5

CRN 75-21-8

CMF C2 H4 O



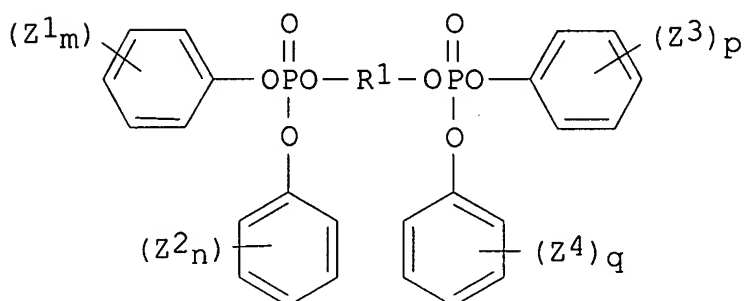
IT **552-30-7DP**, Trimellitic anhydride, reaction products with maleic anhydride, ammonia, amine-contg. polyoxyalkylenes, fatty amines, oleic acid, and ethanolamine
(prepn. of polyether-modified polymers as leather auxiliaries giving good fullness, softness, and tinctorial properties)
RN 552-30-7 HCA
CN 5-Isobenzofurancarboxylic acid, 1,3-dihydro-1,3-dioxo- (9CI) (CA INDEX NAME)



IC ICM A61K031-765
ICS C08L077-00
INCL 424078370; 525432000
CC 45-2 (Industrial Organic Chemicals, Leather, Fats, and Waxes)
IT **83713-01-3DP**, reaction products with maleic anhydride, ammonia, fatty amines, oleic acid, and ethanolamines
(Jeffamine XTJ 507, Jeffamine XTJ 505; prepn. of polyether-modified polymers as leather auxiliaries giving good fullness, softness, and tinctorial properties)
IT 108-31-6DP, Maleic anhydride, reaction products with amine-contg. polyoxyalkylenes, ammonia, fatty amines, oleic acid, and ethanolamine 109-55-7DP, 3-Aminopropyl-dimethylamine, reaction products with amine-contg. polyoxyalkylenes, maleic anhydride, ammonia, ethanolamine, and oleic acid 112-80-1DP, Oleic acid, reaction products with amine-contg. polyoxyalkylenes, maleic anhydride, fatty amines, ammonia, and ethanolamine 141-43-5DP, Ethanolamine, reaction products with amine-contg. polyoxyalkylenes, maleic anhydride, amines, ammonia, and oleic acid 141-43-5DP, Ethanolamine, reaction products with amine-contg. polyoxyalkylenes, maleic anhydride, fatty amines, ammonia, and oleic acid
552-30-7DP, Trimellitic anhydride, reaction products with maleic anhydride, ammonia, amine-contg. polyoxyalkylenes, fatty amines, oleic acid, and ethanolamine 7664-41-7DP, Ammonia, reaction products with amine-contg. polyoxyalkylenes, maleic anhydride, fatty amines, oleic acid, and ethanolamine 9046-10-0DP, Jeffamine D 2000, reaction products with maleic anhydride, ammonia, fatty amines, oleic acid, and ethanolamines
(prepn. of polyether-modified polymers as leather auxiliaries giving good fullness, softness, and tinctorial properties)

133:342498 Photosensitive resin composition, photosensitive element and photosensitive laminate using same, and manufacture of flexible printed circuit board and electronic package. Sasahara, Naoki; Tsuchiya, Katsunori (Hitachi Chemical Co., Ltd., Japan). Jpn. Kokai Tokkyo Koho JP 2000310853 A2 20001107, 19 pp. (Japanese). CODEN: JKXXAF. APPLICATION: JP 1999-287294 19991007. PRIORITY: JP 1999-44023 19990223.

GI



AB The title resin compn. contains (a) a binder polymer, (b) an ethylenic unsatd. group-contg. photopolymg. compd., (c) a photopolymn. initiator, (d) an arom. phosphate I [R1 = divalent residue derived from dihydroxybenzene or 2,2-di(p-hydroxyphenyl)propane; Z1-4 = halogen, C1-20 alkyl, C3-10 cycloalkyl, C6-14 aryl, amino, NO2, cyano, SH, allyl, C1-10 alkylmercapto, C1-20 hydroxyalkyl, carboxyalkyl with C1-10 alkyl, acyl with C1-10 alkyl, C1-20 alkoxy, heterocycle-contg. group; m, n, p, q = 0-5], and (e) a tetrazole compd. The photosensitive element comprises a support coated with a photosensitive layer made of the compn. The photosensitive laminate possesses a photosensitive layer made of the compn. on a substrate for flexible printed circuit boards. The laminate is imagewise exposed to radiation for curing the exposed portions and developed to remove the unexposed portions to form a resist pattern so that a flexible printed circuit board is formed and parts are installed on the board to obtain an electronic package. The compn. shows high photosensitivity, alkali-developability, elec. corrosion resistance, and fireproofing properties.

IT **245467-62-3DP**, Jeffamine ED 2001-trimellitic anhydride copolymer, reaction product with polycarboxylic acid, dimer acid, polyisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate

(photoresist contg. arom. phosphate ester and tetrazole for printed circuit board and electronic packaging)

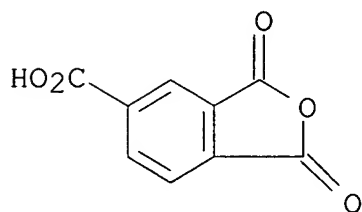
RN 245467-62-3 HCA

CN 5-Isobenzofurancarboxylic acid, 1,3-dihydro-1,3-dioxo-, polymer with methyloxirane polymer with oxirane bis(2-aminopropyl) ether (9CI)
(CA INDEX NAME)

CM 1

CRN 552-30-7

CMF C9 H4 O5



CM 2

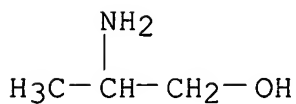
CRN 65605-36-9

CMF C3 H9 N O . 1/2 (C3 H6 O . C2 H4 O) x

CM 3

CRN 6168-72-5

CMF C3 H9 N O



CM 4

CRN 9003-11-6

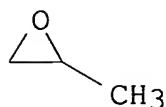
CMF (C3 H6 O . C2 H4 O) x

CCI PMS

CM 5

CRN 75-56-9

CMF C3 H6 O



CM 6

CRN 75-21-8

CMF C2 H4 O



IC ICM G03F007-004
 ICS C08F002-48; G03F007-027; G03F007-032; H05K003-06; H05K003-28
 CC 74-5 (Radiation Chemistry, Photochemistry, and Photographic and
 Other Reprographic Processes)
 Section cross-reference(s): 38, 76
 IT 79-41-4DP, Methacrylic acid, reaction product with
 polyoxyalkylenediimidodicarboxylic acid, polycarboxylic acid, dimer
 acid, polyisocyanate, epoxy resin, and isocyanatoethyl methacrylate
 100-21-0DP, Terephthalic acid, reaction product with
 polyoxyalkylenediimidodicarboxylic acid, dimer acid, polyisocyanate,
 epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate
 101-68-8DP, 4,4'-MDI, reaction product with
 polyoxyalkylenediimidodicarboxylic acid, polycarboxylic acid, dimer
 acid, epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate
 111-20-6DP, Sebacic acid, reaction product with
 polyoxyalkylenediimidodicarboxylic acid, dimer acid, polyisocyanate,
 epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate
 121-91-5DP, Isophthalic acid, reaction product with
 polyoxyalkylenediimidodicarboxylic acid, dimer acid, polyisocyanate,
 epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate
 124-04-9DP, Adipic acid, reaction product with
 polyoxyalkylenediimidodicarboxylic acid, dimer acid, polyisocyanate,
 epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate
 25068-38-6DP, reaction product with polyoxyalkylenediimidodicarboxyl
 ic acid, polycarboxylic acid, dimer acid, polyisocyanate,
 methacrylic acid, and isocyanatoethyl methacrylate 26471-62-5DP,
 TDI, reaction product with polyoxyalkylenediimidodicarboxylic acid,
 polycarboxylic acid, dimer acid, epoxy resin, methacrylic acid, and
 isocyanatoethyl methacrylate 30674-80-7DP, 2-Isocyanatoethyl
 methacrylate, reaction product with polyoxyalkylenediimidodicarboxyli
 c acid, polycarboxylic acid, dimer acid, polyisocyanate, epoxy
 resin, and methacrylic acid 110368-93-9DP, Epotohto YDF 2001,

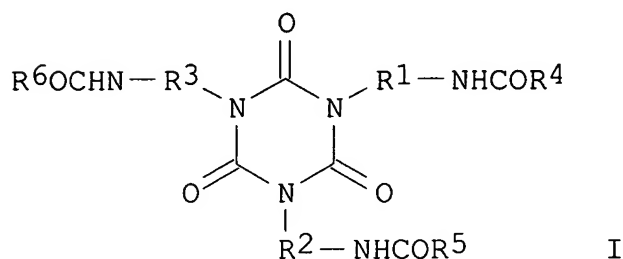
reaction product with polyoxyalkylenediimidodicarboxylic acid, polycarboxylic acid, dimer acid, polyisocyanate, methacrylic acid, and isocyanatoethyl methacrylate 129245-85-8DP, Jeffamine D 2000-trimellitic anhydride copolymer, reaction product with polycarboxylic acid, dimer acid, polyisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate 245445-19-6DP, PEGPA 1000-trimellitic anhydride copolymer, reaction product with polycarboxylic acid, dimer acid, polyisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate **245467-62-3DP**, Jeffamine ED 2001-trimellitic anhydride copolymer, reaction product with polycarboxylic acid, dimer acid, polyisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate

(photoresist contg. arom. phosphate ester and tetrazole for printed circuit board and electronic packaging)

L63 ANSWER 4 OF 8 HCA COPYRIGHT 2006 ACS on STN

132:229504 Photosensitive resin composition, photosensitive element, photosensitive laminate, and manufacture of flexible printed circuit board. Sasahara, Naoki; Ohta, Fumihiko; Kobata, Tatsuko; Amanokura, Hitoshi; Akahori, Akihiko; Suzuki, Kenji (Hitachi Chemical Co., Ltd., Japan). Jpn. Kokai Tokkyo Koho JP 2000075484 A2 20000314, 20 pp. (Japanese). CODEN: JKXXAF. APPLICATION: JP 1998-243417 19980828.

GI



AB The compn. contains (A) an amido-, oxyalkylene-, and CO₂H-contg. resin, (B) an ethylenic unsatd. group-contg. photopolymerizable compd., (C) a photoinitiator, and (D) a block isocyanate having a formula I (R¹-3 = C₁-12 alkylene, C₆-14 arylene; R⁴-6 = residual groups obtained by reaction of isocyanates and active H-contg. compds.). The element has a layer contg. the compn. on a supporting film. The laminate has the layer on a flexible printed circuit board. The manuf. method involves developing the laminate by active energy beam radiation to form a pattern comprising the compn. The compn. is capable of alkali development and shows excellent

sensitivity. The compn. is cured to obtain a compd. with bending, heat soldering, washing, electrocorrosion, and fire resistance and good adhesion.

IT **245467-62-3P**, Jeffamine ED-2001-trimellitic anhydride copolymer

(block isocyanate-based photosensitive resin for manuf. of printed circuit board)

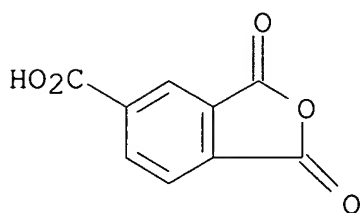
RN 245467-62-3 HCA

CN 5-Isobenzofurancarboxylic acid, 1,3-dihydro-1,3-dioxo-, polymer with methyloxirane polymer with oxirane bis(2-aminopropyl) ether (9CI) (CA INDEX NAME)

CM 1

CRN 552-30-7

CMF C9 H4 O5



CM 2

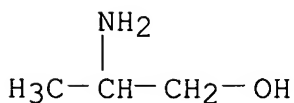
CRN 65605-36-9

CMF C3 H9 N O . 1/2 (C3 H6 O . C2 H4 O)x

CM 3

CRN 6168-72-5

CMF C3 H9 N O



CM 4

CRN 9003-11-6

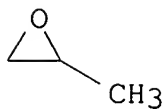
CMF (C3 H6 O . C2 H4 O)x

CCI PMS

CM 5

CRN 75-56-9

CMF C3 H6 O



CM 6

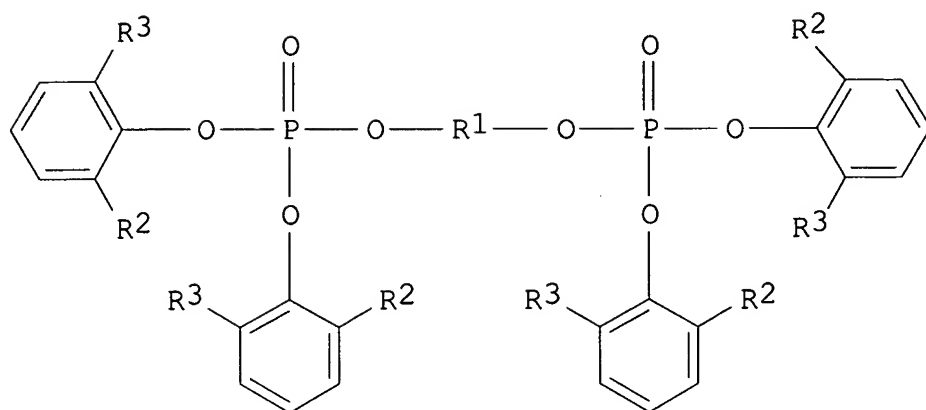
CRN 75-21-8

CMF C2 H4 O



- IC ICM G03F007-033
ICS G03F007-027; G03F007-031; G03F007-09; G03F007-38; H01L021-027;
H05K003-28
- CC 74-5 (Radiation Chemistry, Photochemistry, and Photographic and
Other Reprographic Processes)
Section cross-reference(s): 38
- IT 129245-85-8P, Jeffamine D-2000-trimellitic anhydride copolymer
245445-19-6P, .alpha.,.omega.-(3-Aminopropyl)polyethyleneglycol-
trimellitic anhydride copolymer **245467-62-3P**, Jeffamine
ED-2001-trimellitic anhydride copolymer
(block isocyanate-based photosensitive resin for manuf. of
printed circuit board)
- L63 ANSWER 5 OF 8 HCA COPYRIGHT 2006 ACS on STN
131:279291 Photosensitive polymer composition containing aromatic
phosphate ester, photoresist, laminate of photoresist, and
manufacture of printed circuit board. Akahori, Satohiko; Ota,
Fumihiko; Obata, Tachiko; Amanokura, Hitoshi; Suzuki, Kenji (Hitachi
Chemical Co., Ltd., Japan). Jpn. Kokai Tokkyo Koho JP 11271967 A2
19991008 Heisei, 18 pp. (Japanese). CODEN: JKXXAF. APPLICATION:
JP 1998-75796 19980324.

GI



AB The photosensitive compn. contains a resin contg. amide linkage, oxyalkylene backbone, and carboxyl group, photopolymerizable compd. having ethylenic unsatd. group, a photopolymn. initiator, and arom. phosphate I [R1 = divalent residue after removal of 2 OH from dihydroxybenzene or after removal of 2 OH from 2,2-di(p-hydroxyphenyl)propane; R2 and/or R3 = C1-4 alkyl, the rest is H]. The photoresist has a supporting film and a layer of above compn. and the photoresist is laminated on the surface of a flexible printed circuit board to give title laminate. The laminate is imagewise exposed to active energy ray and developed to give a printed circuit with a pattern showing solder, bending, electrolytic corrosion, and fire resistance.

IT **245467-62-3DP**, Jeffamine ED 2001 trimellitic anhydride copolymer, polymer with dimer acid, dibasic acid, diisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate (photoresist contg. polyoxyalkylene-polyamides, photopolymerizable compds., and arom. phosphates for patterning of flexible printed circuit board)

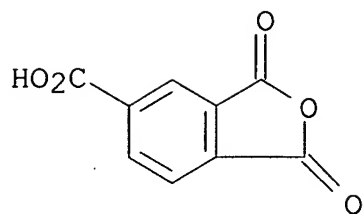
RN 245467-62-3 HCA

CN 5-Isobenzofurancarboxylic acid, 1,3-dihydro-1,3-dioxo-, polymer with methyloxirane polymer with oxirane bis(2-aminopropyl) ether (9CI) (CA INDEX NAME)

CM 1

CRN 552-30-7

CMF C9 H4 O5



CM 2

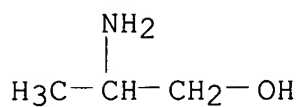
CRN 65605-36-9

CMF C3 H9 N O . 1/2 (C3 H6 O . C2 H4 O) x

CM 3

CRN 6168-72-5

CMF C3 H9 N O



CM 4

CRN 9003-11-6

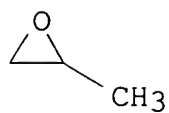
CMF (C3 H6 O . C2 H4 O) x

CCI PMS

CM 5

CRN 75-56-9

CMF C3 H6 O



CM 6

CRN 75-21-8

CMF C2 H4 O



IC ICM G03F007-027
ICS B32B007-02; B32B027-18; C09D163-00; G03F007-004; G03F007-037;
H05K003-28

CC 74-5 (Radiation Chemistry, Photochemistry, and Photographic and
Other Reprographic Processes)
Section cross-reference(s): 38, 76

IT 79-41-4DP, Methacrylic acid, polymer with
polyoxyalkylenediimidodicarboxylic acid, dimer acid, diisocyanate,
epoxy resin, and isocyanatoethyl methacrylate 85-43-8DP,
Tetrahydrophthalic anhydride, polymer with
polyoxyalkylenediimidodicarboxylic acid, dimer acid, diisocyanate,
epoxy resin, and methacrylic acid 100-21-0DP, Terephthalic acid,
polymer with polyoxyalkylenediimidodicarboxylic acid, dimer acid,
diisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl
methacrylate 101-68-8DP, 4,4'-Diphenylmethane diisocyanate,
polymer with polyoxyalkylenediimidodicarboxylic acid, dimer acid,
epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate
111-20-6DP, Sebacic acid, polymer with polyoxyalkylenediimidodicarbo
xylic acid, dimer acid, diisocyanate, epoxy resin, methacrylic acid,
and isocyanatoethyl methacrylate 121-91-5DP, Isophthalic acid,
polymer with polyoxyalkylenediimidodicarboxylic acid, dimer acid,
diisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl
methacrylate 124-04-9DP, Adipic acid, polymer with
polyoxyalkylenediimidodicarboxylic acid, dimer acid, diisocyanate,
epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate
25085-99-8DP, Epomik R 140P, polymer with
polyoxyalkylenediimidodicarboxylic acid, dimer acid, diisocyanate,
methacrylic acid, and isocyanatoethyl methacrylate 26471-62-5DP,
Tolylene diisocyanate, polymer with polyoxyalkylenediimidodicarboxyl
ic acid, dimer acid, epoxy resin, methacrylic acid, and
isocyanatoethyl methacrylate 30674-80-7DP, 2-Isocyanatoethyl
methacrylate, polymer with polyoxyalkylenediimidodicarboxylic acid,
dimer acid, diisocyanate, epoxy resin, and methacrylic acid
64772-16-3DP, Epomik R 301, polymer with
polyoxyalkylenediimidodicarboxylic acid, dimer acid, diisocyanate,
methacrylic acid, and tetrahydrophthalic anhydride 110368-93-9DP,
Epo-Tohto YDF 2001, polymer with polyoxyalkylenediimidodicarboxylic
acid, dimer acid, diisocyanate, methacrylic acid, and
tetrahydrophthalic anhydride 129245-85-8DP, Jeffamine D 2000
trimellitic anhydride copolymer, polymer with dimer acid, dibasic
acid, diisocyanate, epoxy resin, methacrylic acid, and
isocyanatoethyl methacrylate 245445-19-6DP, PEGPA 1000 trimellitic
anhydride copolymer, polymer with dimer acid, dibasic acid,
diisocyanate, epoxy resin, methacrylic acid, and tetrahydrophthalic

anhydride **245467-62-3DP**, Jeffamine ED 2001 trimellitic anhydride copolymer, polymer with dimer acid, dibasic acid, diisocyanate, epoxy resin, methacrylic acid, and isocyanatoethyl methacrylate

(photoresist contg. polyoxyalkylene-polyamides, photopolymerizable compds., and arom. phosphates for patterning of flexible printed circuit board)

L63 ANSWER 6 OF 8 HCA COPYRIGHT 2006 ACS on STN

131:243754 Surface active polyesters. Krishnan, Venkataram (Reichhold, Inc., USA). PCT Int. Appl. WO 9947578 A1 19990923, 49 pp.

DESIGNATED STATES: W: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM; RW: AT, BE, BF, BJ, CF, CG, CH, CI, CM, CY, DE, DK, ES, FI, FR, GA, GB, GR, IE, IT, LU, MC, ML, MR, NE, NL, PT, SE, SN, TD, TG. (English). CODEN: PIXXD2.

APPLICATION: WO 1999-US5594 19990315. PRIORITY: US 1998-PV78156 19980316.

AB The polymers useful as surfactants in emulsion polymn. comprise (a) .gtoreq.1 monomer residue of an arom. dicarboxylic acid bearing a side chain of QC:O (Q = substituent having hydrophilic group, hydrophobic group, or mixts. thereof), (b) .gtoreq.1 monomer residue of an arom. dicarboxylic acid, an aliph. dicarboxylic acid, or mixts. thereof; and (c) .gtoreq.1 monomer residue of an arom. alc., an aliph. alc., or mixts. thereof; wherein the monomer residues of (a), (b), and (c) are arranged to form the backbone of the polymer, and the side chain is a pendant group extending from the polymer backbone. Preferably the polymers are polyesters contg. trimellitic acid having pendant polyoxyethylene side chains.

IT **244159-61-3P**, Jeffamine J 230-trimellitic anhydride copolymer, ester with polyethylene glycol monomethyl ether **244182-93-2P**

(surface active polyesters as surfactants for emulsion polymn.)

RN 244159-61-3 HCA

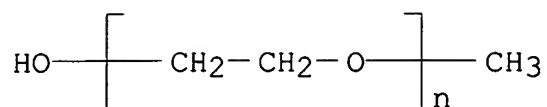
CN 5-Isobenzofurancarboxylic acid, 1,3-dihydro-1,3-dioxo-, polymer with Jeffamine J 230, ester with .alpha.-methyl-.omega.-hydroxypoly(oxy-1,2-ethanediyl), graft (9CI) (CA INDEX NAME)

CM 1

CRN 9004-74-4

CMF (C2 H4 O)n C H4 O

CCI PMS



CM 2

CRN 244159-60-2

CMF (C9 H4 O5 . Unspecified)x

CCI PMS

CM 3

CRN 143637-09-6

CMF Unspecified

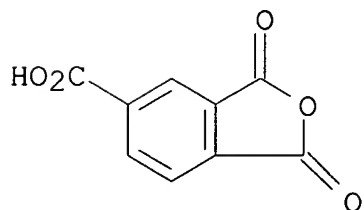
CCI PMS, MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

CM 4

CRN 552-30-7

CMF C9 H4 O5



RN 244182-93-2 HCA

CN 5-Isobenzofurancarboxylic acid, 1,3-dihydro-1,3-dioxo-, polymer with
Jeffamine J 230 and oxirane, methyl ether, graft (9CI) (CA INDEX
NAME)

CM 1

CRN 67-56-1

CMF C H4 O

H₃C-OH

CM 2

CRN 244182-92-1
 CMF (C9 H4 O5 . C2 H4 O . Unspecified)x
 CCI PMS

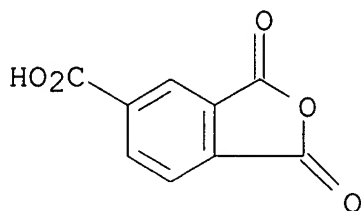
CM 3

CRN 143637-09-6
 CMF Unspecified
 CCI PMS, MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***

CM 4

CRN 552-30-7
 CMF C9 H4 O5



CM 5

CRN 75-21-8
 CMF C2 H4 O



IC ICM C08G063-66
 ICS C08G063-688; C08G063-20; C08G069-44; C08F002-24; C08J003-02;
 B01F017-00
 CC 35-4 (Chemistry of Synthetic High Polymers)
 Section cross-reference(s): 46
 IT 244159-57-7P, Maleic anhydride-neopentyl glycol-phthalic
 anhydride-trimellitic anhydride copolymer, ester with polyethylene
 glycol monomethyl ether 244159-59-9P, Polyethylene
 glycol-5-sulfoisophthalic acid sodium salt-trimellitic anhydride
 copolymer, ester with polyethylene glycol monomethyl ether and Brij
 98 **244159-61-3P**, Jeffamine J 230-trimellitic anhydride
 copolymer, ester with polyethylene glycol monomethyl ether
 244159-62-4P, Polyethylene glycol-trimellitic anhydride copolymer,

ester with polyethylene glycol monomethyl ether 244159-63-5P,
 Neopentyl glycol-trimellitic anhydride copolymer, ester with
 polyethylene glycol monomethyl ether and Igepal CO 210
 244159-64-6P, Polyethylene glycol-trimellitic anhydride copolymer,
 ester with polyethylene glycol monomethyl ether and Igepal CO 210
 244159-65-7P, Polyethylene glycol-trimellitic anhydride copolymer,
 ester with Igepal CO 210 244159-67-9P, Polyethylene
 glycol-2-sulfoterephthalic acid monosodium salt-trimellitic
 anhydride copolymer, ester with Igepal CO 210 244182-83-0P
 244182-85-2P 244182-86-3P 244182-87-4P 244182-89-6P
 244182-91-0P **244182-93-2P** 244182-95-4P

(surface active polyesters as surfactants for emulsion polymn.)

L63 ANSWER 7 OF 8 HCA COPYRIGHT 2006 ACS on STN

106:196914 High-molecular weight diimide diacids and diesters of
 tricarboxylic anhydrides. McCready, Russell James (General Electric
 Co., USA). Eur. Pat. Appl. EP 180149 A2 19860507, 11 pp.
 DESIGNATED STATES: R: DE, FR, GB, IT, NL. (English). CODEN:
 EPXXDW. APPLICATION: EP 1985-113523 19851024. PRIORITY: US
 1984-665192 19841026.

AB The title products are prepd. from tricarboxylic acids with 2
 vicinal CO₂H groups (or their anhydrides) and polyoxyalkylene
 diamines (mol. wt. 600-12,000. Heating 100 parts Jeffamine D 2000
 [polyoxypropylenediamine, mol. wt. .apprx.2000] and 19.2 parts
 trimellitic anhydride with azeotropic distn. of water gave an oily
 dicarboxylic acid. The solvent mixt. was distd. off to leave an
 oily diacid.

IT **99576-59-7P**

(prepn. of)

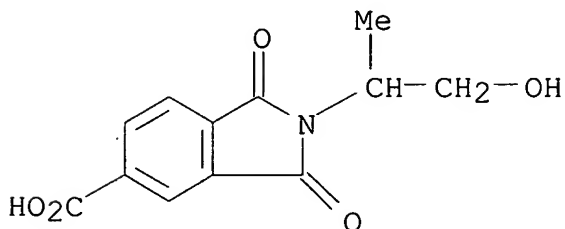
RN 99576-59-7 HCA

CN Oxirane, methyl-, polymer with oxirane, bis[2-(5-carboxy-1,3-dihydro-
 1,3-dioxo-2H-isoindol-2-yl)propyl] ether (9CI) (CA INDEX NAME)

CM 1

CRN 176429-11-1

CMF C12 H11 N O5



CM 2

CRN 9003-11-6

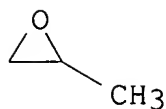
CMF (C3 H6 O . C2 H4 O)x

CCI PMS

CM 3

CRN 75-56-9

CMF C3 H6 O



CM 4

CRN 75-21-8

CMF C2 H4 O



IC ICM C08G065-32

ICS C08G073-10

CC 35-2 (Chemistry of Synthetic High Polymers)

IT 95823-42-0P **99576-59-7P**

(prepn. of)

L63 ANSWER 8 OF 8 HCA COPYRIGHT 2006 ACS on STN

104:7006 Thermoplastic polyether-polyimide-polyester elastomers.

McCready, Russell J. (General Electric Co., USA). U.S. US 4544734 A
 19851001, 7 pp. (English). CODEN: USXXAM. APPLICATION: US
 1984-665315 19841026.

AB The title rubbers are prepd. from diols, dicarboxylic acids, polyoxyalkylene diimide diacids, and dimer acids. The rubbers, with good thermal and oxidative stability, solvent resistance, crystn., and flexibility, are esp. useful in extrusion and molding. Thus, 1,4-butanediol 30, di-Me terephthalate 36, Hystrene 3695 dimer 7, and a diacid prepd. from trimellitic anhydride and Jeffamine ED-900 were heated with tetraoctyl titanate at 180-250.degree. in vacuo until the desired viscosity was obtained. The polymer had m.p. 191.degree. and flexural modulus 19,200 psi, compared with 194 and 25,000, resp., without the dimer acid.

IT **99576-59-7DP**, polymers with butanediol, di-Me terephthalate

and dimer acids

(rubber, thermoplastic, prepn. of, heat- and solvent-resistant)

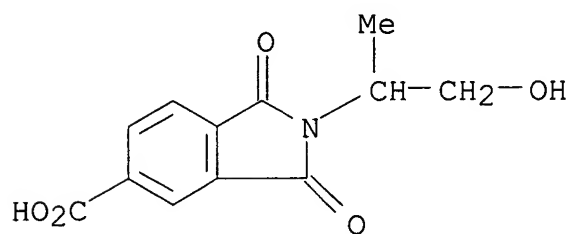
RN 99576-59-7 HCA

CN Oxirane, methyl-, polymer with oxirane, bis[2-(5-carboxy-1,3-dihydro-1,3-dioxo-2H-isoindol-2-yl)propyl] ether (9CI) (CA INDEX NAME)

CM 1

CRN 176429-11-1

CMF C12 H11 N O5



CM 2

CRN 9003-11-6

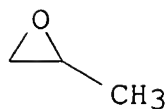
CMF (C3 H6 O . C2 H4 O) x

CCI PMS

CM 3

CRN 75-56-9

CMF C3 H6 O



CM 4

CRN 75-21-8

CMF C2 H4 O



IC ICM C08G063-44

ICS C08G069-44
INCL 528288000
CC 39-4 (Synthetic Elastomers and Natural Rubber)
IT 110-63-4DP, polymers with dimer acids, polyoxyalkylene diimide, and di-Me terephthalate 120-61-6DP, polymers with butanediol, dimer acids, and polyoxyalkylene diimides 95823-42-0DP, polymers with butanediol, di-Me terephthalate and dimer acids **99576-59-7DP**, polymers with butanediol, di-Me terephthalate and dimer acids (rubber, thermoplastic, prepn. of, heat- and solvent-resistant)

(titles below are structurally very poor hits, certainly no ink art.)

=> d 165 1-27 ti

L65 ANSWER 1 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Polyamide-polyimide compositions with good adhesion and fire and solder heat resistance, their adhesive films, and polyimide films laminated with them

L65 ANSWER 2 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Primer with good adhesion for conductor foil and laminate

L65 ANSWER 3 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Aromatic thermoplastic compositions showing good flexibility and heat resistance, and semiconductor devices using them

L65 ANSWER 4 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Adhesive sheet and semiconductor device and its manufacture therewith

L65 ANSWER 5 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Heat- and moisture-resistant composition for adhesive layer in mounting semiconductor chips with small thermal stress

L65 ANSWER 6 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Photosensitive resin composition useful as solder resist and insulating material

L65 ANSWER 7 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Photosensitive resin composition, photosensitive film, and resist pattern formation

L65 ANSWER 8 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Preparation and properties of novel processable polyimides derived from a new diisocyanate

L65 ANSWER 9 OF 27 HCA COPYRIGHT 2006 ACS on STN

- TI Synthesis and characterization of new polyamideimides with a highly flexible soft block
- L65 ANSWER 10 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Photopolymer composition for flexible printed circuit board preparation
- L65 ANSWER 11 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Modified polyamide-imides, their manufacture, and photosensitive compositions containing the resins
- L65 ANSWER 12 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Producing odor-free, air-drying, decorative latex paints containing ethylenically unsaturated compound-based polymers and polyurethanes or polyesters
- L65 ANSWER 13 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Liquid crystal polyimides: 17. Thermotropic poly(ester imide)s based on trimellitimide and diamino oligoether spacers
- L65 ANSWER 14 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Manufacture of reaction injection moldings of polyurea with good coatability and mold releasability
- L65 ANSWER 15 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Crosslinked fine granular resins for coating material
- L65 ANSWER 16 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Polyoxyalkylene-polyimide-polyesters, diacid monomers, and their use for moldings and adhesives
- L65 ANSWER 17 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Vapor-permeable waterproof poly(etherimide) ester elastomer films for medical goods and apparel
- L65 ANSWER 18 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Hindered amine light stabilizers containing aromatic carboxy groups
- L65 ANSWER 19 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Thermoplastic poly(ether imide esters) exhibiting improved flexibility
- L65 ANSWER 20 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Thermoplastic polyetherimide ester polymers exhibiting high flexural modulus
- L65 ANSWER 21 OF 27 HCA COPYRIGHT 2006 ACS on STN
- TI Thermoplastic poly(ether imide esters) exhibiting improved flexural

properties

- L65 ANSWER 22 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Manufacture of thermoplastic poly(etherimide ester) elastomers
- L65 ANSWER 23 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Polyetherimide esters for use as hot-melt adhesives
- L65 ANSWER 24 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Flexible epoxy resins
- L65 ANSWER 25 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Electrically insulating polyester coatings
- L65 ANSWER 26 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Electrically insulating lacquer
- L65 ANSWER 27 OF 27 HCA COPYRIGHT 2006 ACS on STN
TI Resin for electrical insulation